



IPC-A-600H Errata Information – August 2010 (These corrections should be made in user's hard copies in accordance with the company's documented control program)

Sections are in **red**, instructional text in **green**, and corrections in black.

2.3.4 Foreign Inclusions

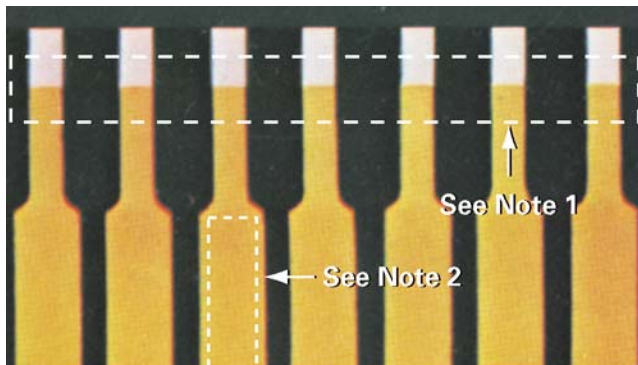
Replace acceptance criteria for Class 1, 2 and 3 with:

Acceptable – Class 1, 2, 3

- Translucent particles trapped within the printed board.
- Opaque particles trapped within the printed board which do not reduce the spacing between adjacent conductors to below the minimum spacing specified.
- Electrical parameters of the printed board are unaffected.

2.7.1 Surface Plating – Plated Contacts

Replace Figure 271a with:



2.9.6 Waves/Wrinkles/Ripples

Replace acceptance criteria for Class 1, 2 and 3 with:

Acceptable - Class 1, 2, 3

- Waves or ripples in the solder mask do not reduce the solder mask coating thickness below the minimum thickness requirements (when specified).
- Wrinkling is located in an area that does not bridge conductive patterns and meets IPC-6010 requirements for solder mask adhesion.

3.3.9 Copper Wrap Plating

Replace acceptance criteria for Class 1, 2 with:

Acceptable - Class 2

- Wrap plating is continuous from the filled plated hole onto the external surface.
- Wrap thickness is not less than 5 μm [197 μin] for all through-hole and via structures.
- Reduction of surface wrap copper plating by processing (sanding, etching, planarization, etc.) does not result in insufficient wrap plating.



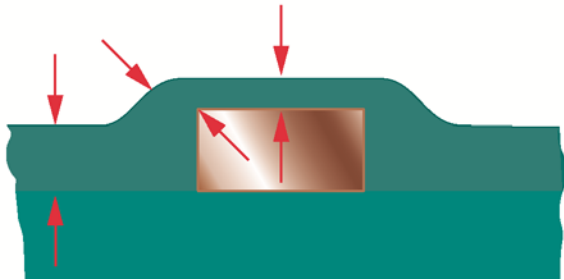
Acceptable - Class 1

- Wrap thickness **shall** be AABUS.

3.3.12 Solder Mask Thickness

Replace Figure 3312b with:

T min, if specified



3.3.16 Material Fill of Blind and Buried Vias

Replace acceptance criteria for Class 1, 2 and 3 with:

Acceptable – Class 2, 3

- At least 60% buried via fill with laminating resin or similar fill material.

Acceptable – Class 2, 3

- At least 60% fill for blind vias with an aspect ratio greater than 1:1 or as specified in the procurement documentation.

Acceptable - Class 1

- Blind and buried vias may be completely void of fill material.

4.1.2.1 Adhesive Squeeze-Out – Land Area

Replace acceptance criteria for Class 1 with:

Acceptable – Class 1

- A solderable annular ring for at least 240° of the circumference.